



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE7241E	Issued	15. March 2021
MA#	MA001110592		
Package	PG-DSO-20-67	Weight*	587.44 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.861	1.85	1.85	18489	18489
leadframe	inorganic material	phosphorus	7723-14-0	0.047	0.01		80	
	non noble metal	zinc	7440-66-6	0.187	0.03		319	
	non noble metal	iron	7439-89-6	3.750	0.64		6383	
	non noble metal	copper	7440-50-8	152.251	25.92	26.60	259180	265962
wire	non noble metal	copper	7440-50-8	0.528	0.09	0.09	899	899
encapsulation	organic material	carbon black	1333-86-4	0.823	0.14		1401	
	plastics	epoxy resin	-	37.847	6.44		64428	
	inorganic material	silicondioxide	60676-86-0	372.714	63.45	70.03	634477	700306
leadfinish	non noble metal	tin	7440-31-5	4.487	0.76	0.76	7638	7638
plating	noble metal	silver	7440-22-4	0.706	0.12	0.12	1202	1202
glue	plastics	epoxy resin	-	0.808	0.14		1376	
	noble metal	silver	7440-22-4	2.425	0.41	0.55	4128	5504
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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